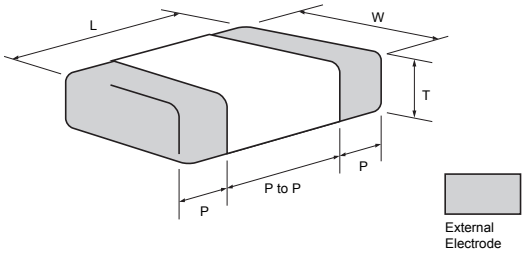
Kyocera Ceramic Chip Capacitors are available for different applications as classified below:

Series	Dieletric Options	Typical Applications	Features	Terminations	Available Size
CM	C0G (NP0) X5R X7R *X6S *X7S Y5V	General Purpose	Wide Cap Range	Nickel Barrier	0201, 0402, 0603 0805, 1206, 1210 1812
CF	C0G (NP0) X7R	High Voltage & Power Circuits	High Voltage 250VDC, 630VDC 1000VDC, 2000VDC 3000VDC, 4000VDC	Nickel Barrier	0805, 1206, 1210 1812, 2208, 1808 2220
CT	C0G (NP0) X5R X7R Y5V	PLCC (Decoupling)	Low Profile	Nickel Barrier	0402, 0603, 0805 1206, 1210
DM	X7R	Automotive	Thermal shock Resistivity High Reliability	Nickel Barrier	0603, 0805, 1206
CA	C0G (NP0) X5R, X7R	Digital Signal Pass line	Reduction in Placing Costs	Nickel Barrier	0405, 0508

* option

Dimensions



Dimensions

Tape & Reel

Size	EIA CODE	JIS CODE	Dimensions (mm)					
			L	W	P min.	P max.	P to P min.	T max.
03	0201	0603	0.6±0.03	0.3±0.03	0.13	0.23	0.20	0.33
05	0402	1005	1.0±0.05	0.5±0.05	0.15	0.35	0.30	0.55
105	0603	1608	1.6±0.10	0.8±0.10	0.20	0.60	0.50	0.90
21	0805	2012	2.0±0.10	1.25±0.10	0.20	0.75	0.70	1.35
316	1206	3216	3.2±0.20	1.60±0.15	0.30	0.85	1.40	1.75
32	1210	3225	3.2±0.20	2.50±0.20	0.30	1.00	1.40	2.70
42	1808	4520	4.5±0.20	2.00±0.20	0.15	0.85	2.60	2.20
43	1812	4532	4.5±0.30	3.20±0.20	0.30	1.10	2.00	3.00
52	2208	5720	5.7±0.40	2.00±0.20	0.15	0.85	4.20	2.20
55	2220	5750	5.7±0.40	5.00±0.40	0.30	1.40	2.50	2.70

• T (Thickness) depends on capacitance value.
Standard thickness is shown on the appropriate product pages.
• CA series (please refer applicable page)
• As for the size of the product specified individually, please contact us.

Bulk Cassette

Size	EIA CODE	JIS CODE	L	W	T	P		P to P
						min.	max.	min.
05	0402	1005	1.0±0.05	0.5±0.05	0.5±0.05	0.15	0.35	0.30
105	0603	1608	1.6±0.07	0.8±0.07	0.8±0.07	0.20	0.60	0.50
21	0805	2012	2.0±0.1	1.25±0.1	1.25±0.1	0.20	0.75	0.70

Note) Regarding support for Bulk cases, please contact us for further information.

Multilayer Ceramic Chip Capacitors
Ordering Information

KYOCERA

KYOCERA PART NUMBER:

CM 21 X7R 104 K 50 A T □□□

SERIES CODE

CM	=	General Purpose	CA	=	Capacitor Arrays
CF	=	High Voltage			
CT	=	Low Profile			
DM	=	Automotive			

SIZE CODE

SIZE	EIA (JIS)	SIZE	EIA (JIS)	SIZE	EIA (JIS)
03	0201 (0603)	21	0805 (2012)	52	2208 (5720)
05	0402 (1005)	316	1206 (3216)	55	2220 (5750)
105	0603 (1608)	32	1210 (3225)	D11	0405 (1012)/ 2cap
F12	0508 (1220)/ 4cap	42	1808 (4520)	D12	0508 (1220)/ 2cap
		43	1812 (4532)		

DIELECTRIC CODE

CODE	EIA CODE		
CG	C0G (NPO)	X7S	X7S (Option)
X5R	X5R	X6S	X6S (Option)
X7R	X7R	Y5V	Y5V

Negative dielectric types are available on request.

CAPACITANCE CODE

Capacitance expressed in pF. 2 significant digits plus number of zeros.
For Values < 10pF, Letter R denotes decimal point,

eg.	100000pF	= 104	1.5pF	= 1R5
	0.1μF	= 104	0.5pF	= R50
	4700pF	= 472	100μF	= 107

TOLERANCE CODE

A = ±0.05pF (option)	D = ±0.5pF	J = ±5%	Z = –20 to +80%
B = ±0.1pF (option)	F = ±1pF	K = ±10%	
C = ±0.25pF	G = ±2% (option)	M = ±20%	

VOLTAGE CODE

04 = 4VDC	100 = 100VDC	1000 = 1000VDC
06 = 6.3VDC	250 = 250VDC	2000 = 2000VDC
10 = 10VDC	400 = 400VDC	3000 = 3000VDC
16 = 16VDC	630 = 630VDC	4000 = 4000VDC
25 = 25VDC		
35 = 35VDC		
50 = 50VDC		

TERMINATION CODE

A = Nickel Barrier

PACKAGING CODE

B = Bulk	L = 13" Reel Taping & 4mm Cavity pitch
C = Bulk Cassette (option)	H = 7" Reel Taping & 2mm Cavity pitch
T = 7" Reel Taping & 4mm Cavity pitch	N = 13" Reel Taping & 2mm Cavity pitch

OPTION

Thickness max. value is indicated in CT series
EX. 125 → 1.25mm max.
095 → 0.95mm max.

High Dielectric Constant

EIA Dielectric	Temperature Range	ΔC max.
X5R	–55 to 85°C	±15%
X7R	–55 to 125°C	
*X7S	–55 to 125°C	±22%
*X6S	–55 to 105°C	
Y5V	–30 to 85°C	–82 to +22%

* option

Temperature Compensation Type

Electric Code Value (pF)	C0G	UΔ N750	SL +350 to –1000
0.5 to 2.7	CK	UK	SL
3.0 to 3.9	CJ	UJ	SL
4.0 to 9.0	CH	UJ	SL
≥10	CG	UJ	SL

K = ±250ppm/ °C, J = ±120ppm/ °C, H = ±60ppm/ °C, G = ±30ppm/ °C
e.g. CG = 0±30ppm/ °C

Note: All parts will be marked as "CG" but will conform to the above table.

Available Tolerances

Dielectric materials, capacitance values and tolerances are available in the following combinations only:

EIA Dielectric	Tolerance	Capacitance
COG	C=±0.25pF D=±0.50pF F=±1pF	*1 <10pF
	*3 A=±0.05pF B=±0.1pF	<0.5pF ≤5pF
	*3 G=±2% J=±5% K=±10%	≥10pF E12 Series
X5R X6R X7R	*2 K=±10% M=±20%	E6 Series
Y5V	Z=–20% to +80%	E3 Series

Note:
*1 Nominal values below 10pF are available in the standard values of 0.5pF, 1.0pF, 1.5pF, 2.0pF, 3.0pF, 4.0pF, 5.0pF, 6.0pF, 7.0pF, 8.0pF, 9.0pF
*2 J = ±5% for X7R (X5R) is available on request.
*3 option

E Standard Number

E3	E6	E12	E24 (Option)	
1.0	1.0	1.0	1.0	1.1
		1.2	1.2	1.3
	1.5	1.5	1.5	1.6
		1.8	1.8	2.0
2.2	2.2	2.2	2.2	2.4
		2.7	2.7	3.0
	3.3	3.3	3.3	3.6
		3.9	3.9	4.3
4.7	4.7	4.7	4.7	5.1
		5.6	5.6	6.2
	6.8	6.8	6.8	7.5
		8.2	8.2	9.1

CM Series
Nickel Barrier Terminations

[RoHS Compliant Products]

Features

We offer a diverse product line ranging from ultra–compact (0.6×0.3mm) to large (4.3×3.2mm) components configured for a variety of temperature characteristics, rated voltages, and packages. We offer the choice and flexibility for almost any applications.

Applications

This standard type is ideal for use in a wide range of applications, from commercial to industrial equipment.

Temperature Compensation Dielectric

Size (EIA Code)	CM03 (0201)					CM05 (0402)			CM105 (0603)		CM21 (0805)			
Temperature Characteristics	CΔ		UΔ		SL	CΔ	UΔ	SL	CΔ		CΔ			
Rated Voltage (VDC) / Capacitance (pF)	25	50	16	25	25	50	50	50	50	100	16	25	50	100
R20 0.2 R50 0.5 1R0 1.0 1R5 1.5	A		A			B				C				
2.0 3.0 4.0		A		A	A		B	B						
5.0 6.0 7.0														
8.0 9.0 100 10	A													
120 12 15 18									C					
22 27 33		A		A	A	B	B	B		C				
39 47 56														
68 82 101 100														D
121 120 150 180									C					
220 270 330													D	
390 470 560														
680 820 102 1000													E	
122 1200 1500 1800												E		
2200 2700 3300												G		
3900 4700 5600											G			
6800 8200 103 10000														
123 12000 15000 18000														

Thickness and standard package quantity

Size	*03	*05	105	*105	21, 316, 32								
Thickness (mm)	A	B	C	C	D	E	F	G	H	I	J	K	L
	0.3±0.03	0.5±0.05	0.8±0.1	0.8±0.1	0.6±0.1	0.85±0.1	1.15±0.1	1.25±0.1	1.4 max.	1.6 max.	1.6±0.15	2.0±0.2	2.5±0.2
Taping (180 dia reel)	15kp (P8)	10kp (P8)	4kp (P8)	8kp (P8)	4kp (P8)	4kp (P8)	3kp (E8)	3kp (E8)	3kp (E8)	2.5kp (E8)	2.5kp (E8)	2kp (E8)	1kp (E8)
Taping (330 dia reel)	50kp (P8)	50kp (P8)	10kp (P8)	20kp (P8)	10kp (P8)	10kp (P8)	10kp (E8)	10kp (E8)	10kp (E8)	5kp (E8)	5kp (E8)	5kp (E8)	—

Size	43			
Thickness (mm)	J	K	L	M
	1.6±0.15	2.0±0.2	2.5±0.2	2.8±0.2
Taping (180 dia reel)	1kp (E12)	1kp (E12)	0.5kp (E12)	0.5kp (E12)
Taping (330 dia reel)	—	—	—	—

Note: P8 = 8mm width paper tape
E8 = 8mm width plastic tape
E12 = 12mm width plastic tape

* Carrier tape 2mm pitch from one capacitor to another.

X5R Dielectric

Size (EIA Code)		CM03 (0201)					CM05 (0402)						CM105 (0603)						CM21 (0805)					
Rated Voltage (VDC) / Capacitance (pF)		4	6.3	10	16	25	4	6.3	10	16	25	50	4	6.3	10	16	25	50	4	6.3	10	16	25	50
101	100																							
151	150					A						B												
	220																							
	330																							
	470																							
	680				A																			
102	1000																							
152	1500																							
	2200			A																				
	3300																							
	4700										B							C						
	6800																							
103	10000																							
153	15000									B							C	C						D
	22000																							E
	33000																							
	47000																	C						G
	68000																							
104	100000																	C						
154	150000							B								C							G	
	220000																							
	330000																							
	470000														C							G		
	680000																							
105	1000000																							
155	1500000																				G	G		
	2200000																							
	3300000																							
	4700000																			G	G			
	6800000																							
106	10000000																							
156	15000000																							
	22000000																							
476	33000000																							
	47000000																							

Size (EIA Code)		CM316 (1206)					CM32 (1210)						CM43 (1812)	
Rated Voltage (VDC) / Capacitance (pF)		6.3	10	16	25	50	4	6.3	10	16	25	50	6.3	50
104	100000													
	220000				F	F								
	470000										H	H		
105	1000000				J						K	K		L
	2200000	J	J	J					K	I	L			
	4700000							L	L	L				
106	10000000													
	22000000												M	
	47000000													
107	100000000													

Optional Spec.

Thickness and standard package quantity

Size	*03	*05	105	*105	21, 316, 32								
Thickness (mm)	A	B	C	C	D	E	F	G	H	I	J	K	L
	0.3±0.03	0.5±0.05	0.8±0.1	0.8±0.1	0.6±0.1	0.85±0.1	1.15±0.1	1.25±0.1	1.4 max.	1.6 max.	1.6±0.15	2.0±0.2	2.5±0.2
Taping (180 dia reel)	15kp (P8)	10kp (P8)	4kp (P8)	8kp (P8)	4kp (P8)	4kp (P8)	3kp (E8)	3kp (E8)	3kp (E8)	2.5kp (E8)	2.5kp (E8)	2kp (E8)	1kp (E8)
Taping (330 dia reel)	50kp (P8)	50kp (P8)	10kp (P8)	20kp (P8)	10kp (P8)	10kp (P8)	10kp (E8)	10kp (E8)	10kp (E8)	5kp (E8)	5kp (E8)	5kp (E8)	—

Size	43			
Thickness (mm)	J	K	L	M
	1.6±0.15	2.0±0.2	2.5±0.2	2.8±0.2
Taping (180 dia reel)	1kp (E12)	1kp (E12)	0.5kp (E12)	0.5kp (E12)
Taping (330 dia reel)	—	—	—	—

Note: P8 = 8mm width paper tape
E8 = 8mm width plastic tape
E12 = 12mm width plastic tape

* Carrier tape 2mm pitch from one capacitor to another.

CM Series
Nickel Barrier Terminations

KYOCERA

[RoHS Compliant Products]

X7R, Dielectric

Size (EIA Code)	CM03 (0201)			CM05 (0402)			CM105 (0603)						CM21 (0805)					
Rated Voltage (VDC) / Capacitance (pF)	10	16	25	16	25	50	6.3	10	16	25	50	100	6.3	10	16	25	50	100
101 100																		
151 150		A	A			B						C						
220																		
330																		
470																		
680																		
102 1000																		
152 1500	A			B	B					C	C						D E	
2200																		G
3300																		
4700				B						C	C					D E		
6800																		
103 10000									C	C	C				G		G	
153 15000								C						G		G		
22000																		
33000																		
47000																		
68000																		
104 100000																		
154 150000																		
220000																		
330000																		
470000																		
680000																		
105 1000000																		
155 1500000																		
2200000																		
3300000																		
4700000																		
106 10000000																		

Size (EIA Code)	CM316 (1206)						CM32 (1210)					CM43 (1812)	
Rated Voltage (VDC) / Capacitance (pF)	6.3	10	16	25	50	100	10	16	25	50	100	50	100
103 10000													
22000													
47000					E	F					H		
104 100000					F	J					K		
220000				F						H	L	K	L
470000				F						H		L	
105 1000000		J	F	J					H	K			
2200000							L	L	K				
4700000													
106 10000000													
22000000													

Optional Spec.

Y5V Dielectric

Size (EIA Code)	CM03 (0201)		CM05 (0402)				CM105 (0603)				CM21 (0805)				CM316 (1206)			CM32 (1210)		
Rated Voltage (VDC) / Capacitance (pF)	6.3	10	10	16	25	50	10	16	25	50	10	16	25	50	10	16	25	10	16	25
102 1000																				
2200		A																		
472 4700						B														
103 10000	A				B					C										
22000				B					C											
473 47000													D	E						
104 100000			B					C				E	E							
220000													G	G						
474 470000							C				G	G				F	F			
105 1000000															J	J		K	I	I
2200000																				
475 4700000																				
106 10000000																				
22000000																				
476 47000000																				

Thickness and standard package quantity

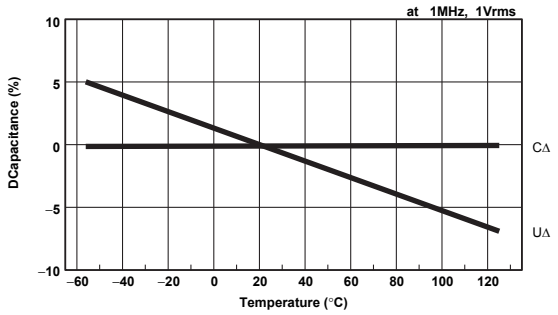
Size	*03	*05	105	*105	21, 316, 32								
Thickness (mm)	A	B	C	C	D	E	F	G	H	I	J	K	L
	0.3±0.03	0.5±0.05	0.8±0.1	0.8±0.1	0.6±0.1	0.85±0.1	1.15±0.1	1.25±0.1	1.4 max.	1.6 max.	1.6±0.15	2.0±0.2	2.5±0.2
Taping (180 dia reel)	15kp (P8)	10kp (P8)	4kp (P8)	8kp (P8)	4kp (P8)	4kp (P8)	3kp (E8)	3kp (E8)	3kp (E8)	2.5kp (E8)	2.5kp (E8)	2kp (E8)	1kp (E8)
Taping (330 dia reel)	50kp (P8)	50kp (P8)	10kp (P8)	20kp (P8)	10kp (P8)	10kp (P8)	10kp (E8)	10kp (E8)	10kp (E8)	5kp (E8)	5kp (E8)	5kp (E8)	—

Size	43			
Thickness (mm)	J	K	L	M
	1.6±0.15	2.0±0.2	2.5±0.2	2.8±0.2
Taping (180 dia reel)	1kp (E12)	1kp (E12)	0.5kp (E12)	0.5kp (E12)
Taping (330 dia reel)	—	—	—	—

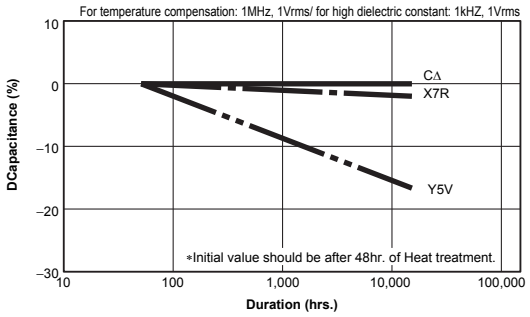
Note: P8 = 8mm width paper tape
E8 = 8mm width plastic tape
E12 = 12mm width plastic tape

* Carrier tape 2mm pitch from one capacitor to another.

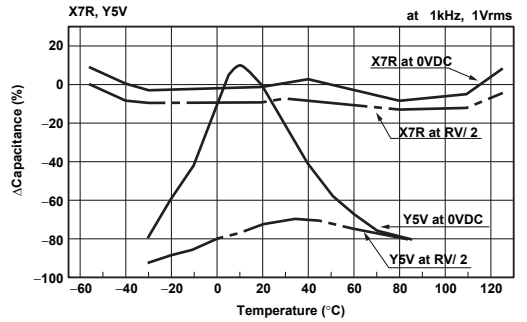
Capacitance-Temperature (temperature compensation)



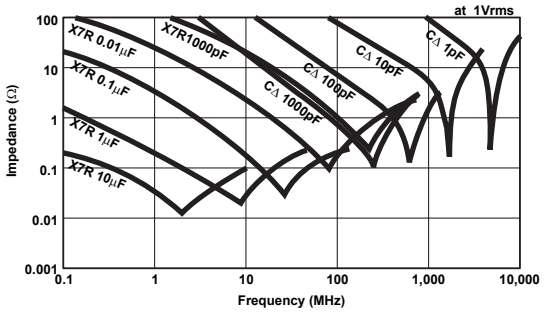
Aging (change of capacitance over time)



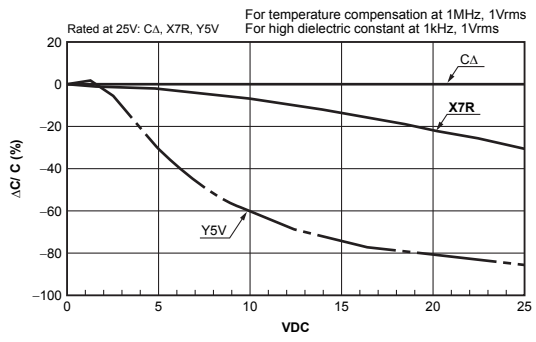
Capacitance-Temperature (high dielectric constant)



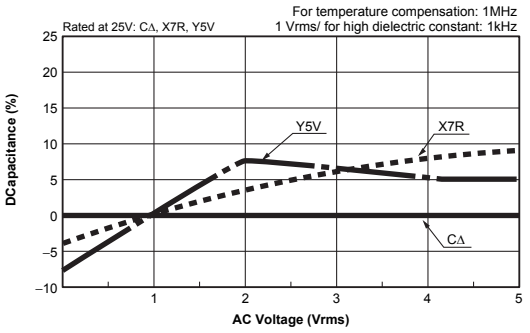
Impedance-Frequency



DC Bias



AC Voltage



Please verify individual characteristics at the design stage to ensure total suitability.

Test Conditions and Specifications for Temperature Compensation type (CΔ to UΔ • SL Characteristics)

<table>
<tr><th colspan="2">Test Items</th><th>Specifications (C: nominal capacitance)</th><th>Test Conditions</th></tr>
<tr><td colspan="2">Capacitance Value</td><td>Within tolerance</td><td rowspan="2"><table><tr><td>C≤1000pF</td><td>1MHz±10%</td><td rowspan="2">0.5 to 5Vrms</td></tr><tr><td>C>1000pF</td><td>1kHz±10%</td></tr></table></td></tr>
<tr><td colspan="2">Q</td><td>C≥30pF: Q≥1000
C<30pF: Q≥400+20C</td></tr>
<tr><td colspan="2">Insulation resistance (IR) (*5)</td><td>10,000MΩ or 500MΩ • μF min., whichever is less</td><td>Measured after the rated voltage is applied for one minute at normal room temperature and humidity. (*3)</td></tr>
<tr><td colspan="2">Dielectric resistance (*5)</td><td>No problem observed</td><td>(*1) Apply 3 times of the rated voltage for 1 to 5 seconds.</td></tr>
<tr><td colspan="2">Appearance</td><td>No problem observed</td><td>Microscope (10×magnification)</td></tr>
<tr><td colspan="2">Termination strength</td><td>No problem observed</td><td>Apply a sideward force of 500g (5N) (*2) to a PCB–mounted sample.</td></tr>
<tr><td colspan="2">Bending strength</td><td>No mechanical damage at 1mm bent</td><td>Glass epoxy PCB (t=1.6mm); fulcrum Spacing: 90mm; for 10 seconds.</td></tr>
<tr><td rowspan="3">Vibration test</td><td>Appearance</td><td>No significant change is detected</td><td rowspan="3">Vibration frequency: 10 to 55 (Hz)
Amplitude: 1.5mm
Sweeping condition: 10→55→10Hz/ min.
In X, Y and Z directions:
2 hours each Total 6 hours</td></tr>
<tr><td>ΔC</td><td>Within tolerance</td></tr>
<tr><td>Q</td><td>C≥30pF: Q≥1000
C<30pF: Q≥400+20C</td></tr>
<tr><td rowspan="5">Soldering heat resistance</td><td>Appearance</td><td>No significant change is detected</td><td rowspan="5">Soak the sample in 260°C±5°C solder for 10±0.5 seconds and place in a room at normal temperature and humidity; measure after 24±2 hours.
(Preheating Conditions)<table><tr><th>Order</th><th>Temperature</th><th>Time</th></tr><tr><td>1</td><td>80 to 100°C</td><td>2 minutes</td></tr><tr><td>2</td><td>150 to 200°C</td><td>2 minutes</td></tr></table></td></tr>
<tr><td>ΔC</td><td>±2.5% or ±0.25pF max., whichever is larger</td></tr>
<tr><td>Q</td><td>C≥30pF: Q≥1000
C<30pF: Q≥400+20C</td></tr>
<tr><td>IR (*5)</td><td>10,000MΩ or 500MΩ • μF min., whichever is smaller</td></tr>
<tr><td>Withstand voltage(*5)</td><td>Resists without problem</td></tr>
<tr><td colspan="2">Solderability</td><td>Ni/ Br termination: 90% min.</td><td>Soaking Condition<table><tr><td>Sn63 Solder</td><td>235±5°C</td><td>2±0.5 sec.</td></tr><tr><td>Sn-3Ag-0.5Cu</td><td>245±5°C</td><td>3±0.5 sec.</td></tr></table></td></tr>
<tr><td rowspan="5">Temperature cycle</td><td>Appearance</td><td>No significant change is detected</td><td rowspan="5">(Cycle)
Normal room temperature (3 min.) →
Lowest operation temperature (30 min.) →
Normal room temperature (3 min.) →
Highest operation temperature (30 min.) →

After five cycles, measure after 24±2 hours.</td></tr>
<tr><td>ΔC</td><td>±2.5% or ±0.25pF max., whichever is larger</td></tr>
<tr><td>Q</td><td>C≥30pF: Q≥1000
C<30pF: Q≥400+20C</td></tr>
<tr><td>IR (*5)</td><td>10,000MΩ or 500MΩ • μF min., whichever is smaller</td></tr>
<tr><td>Withstand voltage(*5)</td><td>Resists without problem</td></tr>
<tr><td rowspan="4">Load humidity test (*4)</td><td>Appearance</td><td>No significant change is detected</td><td rowspan="4">After appling rated voltage for 500+24/ –0 hours in pre–condition at 40±2°C, humidity 90 to 95%RH allow parts to stabilize for 48±4 hours, at room temperature before making measurements.</td></tr>
<tr><td>ΔC</td><td>±7.5% or ±0.75pF max., whichever is larger</td></tr>
<tr><td>Q</td><td>C≥30pF: Q≥200
C<30pF: Q≥100+10C/ 3</td></tr>
<tr><td>IR (*5)</td><td>500MΩ or 25MΩ • μF min., whichever is smaller</td></tr>
<tr><td rowspan="4">High–temperature with loading</td><td>Appearance</td><td>No significant change is detected</td><td rowspan="4">After applying (*1) twice of the rated voltage at a temperature of 125±3°C for 1000+48/ –0 hours, measure the sample after storing 24±2 hours.</td></tr>
<tr><td>ΔC</td><td>±3% or ±0.3pF max., whichever is larger</td></tr>
<tr><td>Q</td><td>C≥30pF: Q≥350
10pF≤C<30pF: Q≥275+5C/ 2
C<10pF: Q≥200+10C</td></tr>
<tr><td>IR (*5)</td><td>1,000MΩ or 50MΩ • μF min., whichever is smaller</td></tr>
</table>

*1 For the CF series, use 1.5 times when the rated voltage is 250V; use/ 1.2 times when the rated voltage exceeds 630V.
*2 2N at 0201 Size
*3 Apply 500V for 1 minute in case the rated voltage is 630V or higher.
*4 Except CF series.
*5 The charge and discharge current of the capacitor must not exceed 50mA.

Test Conditions and Specifications for High Dielectric Type (X5R, X7R, Y5V)

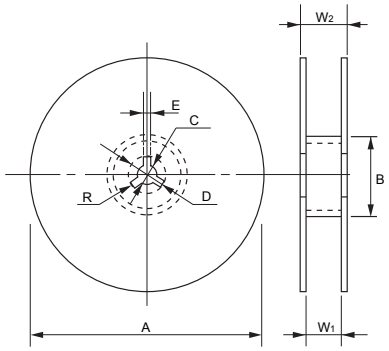
Test Items		Specifications		Test Conditions
		X7R/ X5R	Y5V	
Capacitance Value		Within tolerance		Do previous treatment (*8, *14) Capacitance: C≤10μF: Fire 1kHz±10%, Vol 1.0±0.2Vrms; C>10μF: Fire 120Hz±10%, Vol 0.5±0.2Vrms
tanδ (%)		2.5% max., 3.5% max. (*2), 7.0% max. (*12) 5.0% max. (*3), 7.5% max. (*17)	5.0% max., 7.0% max. (*13) 9.0% max. (*4), 12.5% max. (*5)	
Insulation resistance (IR) (*15)		10,000MΩ or 500MΩ・μF min., whichever is less		Measured after the rated voltage is applied for 2 minutes at normal room temperature and humidity. (*10)
Dielectric resistance (*15)		No problem observed		(*1) Apply 2.5 times of the rated voltage for 1 to 5 seconds.
Appearance		No problem observed		Microscope (10×magnification)
Termination strength (*6)		No problem observed		Apply a sideward force of 500g (5N) (*16) to a PCB–mounted sample.
Bending strength test (*6)		No problem observed at 1mm bent		Glass epoxy PCB (*03, 05 type and CA Series: T=0.8mm); fulcrum Spacing: 90mm; for 10 seconds.
Vibration test	**Appearance**	No significant change is detected		Vibration frequency: 10 to 55 (Hz) Amplitude: 1.5mm Sweeping condition: 10→55→10Hz/ min. In X, Y and Z directions: 2 hours each Total 6 hours
	ΔC	Within tolerance		
	tanδ (%)	Satisfies the initial value		
Soldering heat resistance	**Appearance**	No significant change is detected		Do previous treatment (*8) Soak the sample in 260°C±5°C solder for 10±0.5 seconds and place in a room at normal temperature and humidity; measure after 48±4 hours. (Preheating Conditions) 1: 80 to 100°C, 2 minutes 2: 150 to 200°C, 2 minutes
	ΔC	Within ±7.5%	Within ±20%	
	tanδ (%)	Satisfies the initial value		
	IR (*15)	10,000MΩ or 500MΩ・μF min., whichever is smaller		
	Withstand voltage (*15)	Resists without problem		
Solderability		Ni/ Br termination: 90% min.		Soaking Condition Sn63 Solder: 235±5°C, 2±0.5 sec. Sn-3Ag-0.5Cu: 245±5°C, 3±0.5 sec.
Temperature cycle	**Appearance**	No significant change is detected		Do previous treatment (*8) (Cycle) Normal room temperature (3 min.) → Lowest operation temperature (30 min.) → Normal room temperature (3 min.) → Highest operation temperature (30 min.) → After five cycles, measure after 48±4hours.
	ΔC	Within ±7.5%	Within ±20%	
	tanδ (%)	Satisfies the initial value		
	IR (*15)	10,000MΩ or 500MΩ・μF min., whichever is smaller		
	Withstand voltage (*15)	Resists without problem		
Load humidity test (*11)	**Appearance**	No significant change is detected		Do previous treatment (*9) After applying rated voltage at 40±2°C and humidty 90 to 95%RH, for 500+24/ −0 hours and keep at room condition for 48±4 hours then measure and check the specification limits.
	ΔC	Within ±12.5%	Within ±30%	
	tanδ (%)	200% max. of initial value	150% max. of initial value	
	IR (*15)	500MΩ or 25MΩ・μF min., whichever is smaller		
High–temperature with loading	**Appearance**	No significant change is detected		Do previous treatment (*9) After applying twice (*7) of the rated voltage at the highest operating temperature for 1000+48/ −0 hours, measure the sample after storing 48±4 hours.
	ΔC	Within ±12.5%	Within ±30%	
	tanδ (%)	200% max. of initial value	150% max. of initial value	
	IR (*15)	1,000MΩ or 50MΩ・μF min., whichever is smaller		

*1 Use 1.5 times when the rated voltage is 250V or over.
Use 1.2 times when the rated voltage is 630V or over.
*2 X7R 16V/ 25V type.
*3 Apply to X5R16V/ 25V type, X7R 6.3V/ 10V type.
*4 Apply to Y5V 16V type, CM32Y5V335 to 106 (25V Type).
*5 Apply to Y5V 6.3V/ 10V type. Apply 16% max. to CM21Y5V106/ CM316Y5V226.
*6 Exclude CT series with thickness of less than 0.66mm and CA series.
*7 Use 1.5 times when the rated voltage is 4V/ 6.3V/ 10V/ 250V and 100V (32X7R474/ 43X7R105/ 55X7R105).
Use 1.2 times when the rated voltage is 630V or over.
*8 Keep specimen at 150°C+0/ −10°C for one hour, leave specimen at room ambient for 48±4 hours.
*9 Apply the same test condition for one hour, then leave the specimen at room ambient for 48±4 hours.
*10 For the CF series over 630V, apply 500V for 1 minute at room ambient.
*11 Except CF series.
*12 Apply to X5R 10V type.
*13 Apply to 25V series of CM105Y5V154 over, CM21Y5V105 over, 316Y5V155 over.
*14 Measurement condition 1kHz, 1Vrms for Y5V, C<47μF type.
*15 The charge/ discharge current of the capacitor must not exceed 50mA.
*16 2N at 0201 Size
*17 Apply to X5R 4V and 6.3V type.

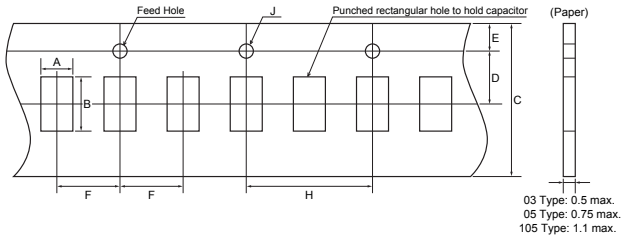
* The above test conditions and standards do not apply to products with optional specifications.

Tape and Reel

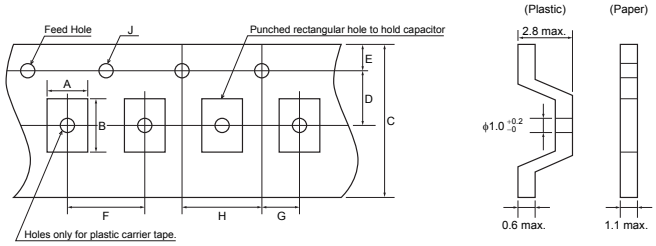
• Reel



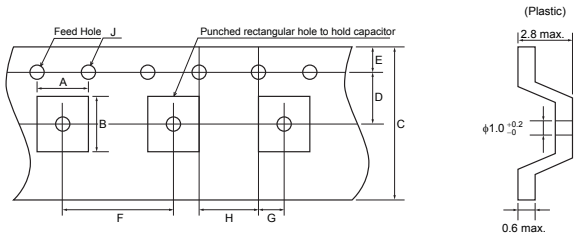
F=2mm (03, 05, 105 Type)



F=4mm (105, D11, D12, F12, 21, 316, 32, 42, 52 Type)

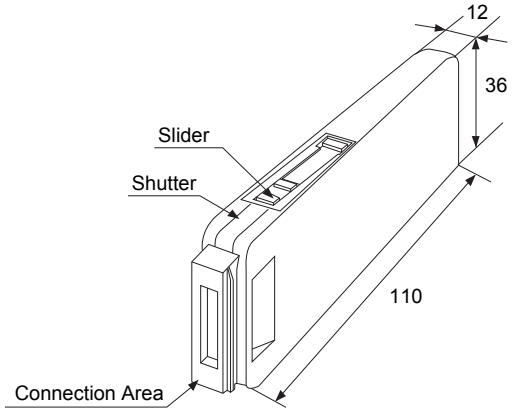


F=8mm (43, 55 Type)



Bulk Cassette

(Unit: mm)



Reel

(Unit: mm)

Code / Reel	A	B	C	D
7–inch Reel (CODE: T, H)	180 $^{+0}_{-2.0}$	ϕ60 min.	13±0.5	21±0.8
13–inch Reel (CODE: L, N)	330±2.0	ϕ100±1.0		
Code / Reel	**E**	**W1**	**W2**	**R**
7–inch Reel (CODE: T, H)	2.0±0.5	10.0±1.5	16.5 max.	1.0
13–inch Reel (CODE: L, N)		9.5±1.0		

∗ Carrier tape width 8mm.
For size 42 (1808) or over, Tape width 12mm and W1: 14±1.5, W2: 18.4mm max.

Carrier Tape

(Unit: mm)

Type	A	B	F
03 (0.6×0.3)	0.37±0.03	0.67±0.03	2.0±0.05
05 (1.0×0.5)	0.65±0.1	1.15±0.1	2.0±0.05
105 (1.6×0.8)	1.0±0.2	1.8±0.2	4.0±0.1
D11 (1.37×1.0)	1.15±0.2	1.55±0.2	4.0±0.1
D12 (1.25×2.0)	1.5±0.2	2.3±0.2	4.0±0.1
F12 (1.25×2.0)	1.5±0.2	2.3±0.2	4.0±0.1
21 (2.0×1.25)	1.5±0.2	2.3±0.2	4.0±0.1
316 (3.2×1.6)	2.0±0.2	3.6±0.2	4.0±0.1
32 (3.2×2.5)	2.9±0.2	3.6±0.2	4.0±0.1
42 (4.5×2.0)	2.4±0.2	4.9±0.2	4.0±0.1
43 (4.5×3.2)	3.6±0.2	4.9±0.2	8.0±0.1
52 (5.7×2.0)	2.4±0.2	6.0±0.2	4.0±0.1
55 (5.7×5.0)	5.3±0.2	6.0±0.2	8.0±0.1

(Unit: mm)

F	Carrier Tape	C	D	E	G	H	J
2.0 ±0.05	8mm Paper	8.0 ±0.3	3.5 ±0.05	1.75 ±0.1	2.0 ±0.05	4.0 ±0.1	1.5 +0.1/ −0
4.0 ±0.1	8mm Plastic						
8.0 ±0.1	12mm Plastic	12.0 ±0.3	5.5 ±0.05				

Multilayer Ceramic Chip Capacitors
Precautions

Circuit Design

1. Once application and assembly environments have been checked, the capacitor may be used in conformance with the rating and performance which are provided in both the catalog and the specifications. Use exceeding that which is specified may result in inferior performance or cause a short, open, smoking, or flaming to occur, etc.

2. Please consult the manufacturer in advance when the capacitor is used in devices such as: devices which deal with human life, i.e. medical devices; devices which are highly public orientated; and devices which demand a high standard of liability.
   Accident or malfunction of devices such as medical devices, space equipment and devices having to do with atomic power could generate grave consequence with respect to human lives or, possibly, a portion of the public. Capacitors used in these devices may require high reliability design different from that of general purpose capacitors.

3. Please use the capacitors in conformance with the operating temperature provided in both the catalog and the specifications.
   Be especially cautious not to exceed the maximum temperature. In the situation the maximum temperature set forth in both the catalog and specifications is exceeded, the capacitor's insulation resistance may deteriorate, power may suddenly surge and short–circuit may occur.
   The capacitor has a loss, and may self–heat due to equivalent series resistance when alternating electric current is passed therethrough. As this effect becomes especially pronounced in high frequency circuits, please exercise caution.
   When using the capacitor in a (self–heating) circuit, please make sure the surface of the capacitor remains under the maximum temperature for usage. Also, please make certain temperature rises remain below 20°C.

4. Please keep voltage under the rated voltage which is applied to the capacitor. Also, please make certain the peak voltage remains below the rated voltage when AC voltage is super–imposed to the DC voltage.
   In the situation where AC or pulse voltage is employed, ensure average peak voltage does not exceed the rated voltage.
   Exceeding the rated voltage provided in both catalog and specifications may lead to defective withstanding voltage or, in worst case situations, may cause the capacitor to smoke or flame.

5. When the capacitor is to be employed in a circuit in which there is continuous application of a high frequency voltage or a steep pulse voltage, even though it is within the rated voltage, please inquire to the manufacturer.
   In the situation the capacitor is to be employed using a high frequency AC voltage or a extremely fast rising pulse voltage, even though it is within the rated voltage, it is possible capacitor reliability will deteriorate.

6. It is a common phenomenon of high–dielectric products to have a deteriorated amount of static electricity due to the application of DC voltage. Due caution is necessary as the degree of deterioration varies depending on the quality of capacitor materials, capacity, as well as the load voltage at the time of operation.

7. Do not use the capacitor in an environment where it might easily exceed the respective provisions concerning shock and vibration specified in the catalog and specifications.
   In addition, it is a common piezo phenomenon of high dielectric products to have some voltage due to vibration or to have noise due to voltage change. Please contact sales in such case.

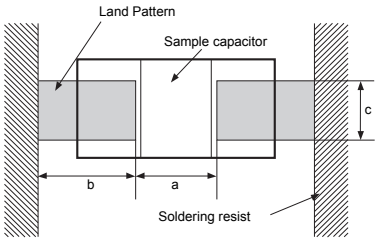
8. If the electrostatic capacity value of the delivered capacitor is within the specified tolerance, please consider this when designing the respective product in order that the assembled product function appropriately.

9. Please contact us upon using conductive adhesives.

Storage

1. If the component is stored in minimal packaging (a heat–sealed or chuck–type plastic bag), the bag should be kept closed. Once the bag has been opened, reseal it or store it in a desiccator.
2. Keep storage place temperature +5 to +35 degree C, humidity 45 to 70% RH.
3. The storage atmosphere must be free of gas containing sulfur and chlorine. Also, avoid exposing the product to saline moisture. If the product is exposed to such atmospheres, the terminals will oxidize and solderability will be effected.
4. Precautions 1) to 3) apply to chip capacitors packaged in carrier tapes and bulk cases.
5. The solderability is assured for 12 months from our shipping date (six months for silver palladium) if the above storage precautions are followed.
6. Chip capacitors may crack if exposed to hydrogen (H_2) gas while sealed or if coated with silicon, which generates hydrogen gas.

Dimensions for recommended typical land



When mounting the capacitor to the substrate, it is important to consider carefully that the amount of solder (size of fillet) used has a direct effect upon the capacitor once it is mounted.

a) The greater the amount of solder, the greater the stress to the elements. As this may cause the substrate to break or crack, it is important to establish the appropriate dimensions with regard to the amount of solder when designing the land of the substrate.
b) In the situation where two or more devices are mounted onto a common land, separate the device into exclusive pads by using soldering resist.

Standard

(Unit: mm)

Size	L×W	a	b	c
03	0.6×0.3	0.20 to 0.30	0.25 to 0.35	0.30 to 0.40
05	1.0×0.5	0.30 to 0.50	0.35 to 0.45	0.40 to 0.60
105	1.6×0.8	0.70 to 1.00	0.80 to 1.00	0.60 to 0.80
21	2.0×1.25	1.00 to 1.30	1.00 to 1.20	0.80 to 1.10
316	3.2×1.6	2.10 to 2.50	1.10 to 1.30	1.00 to 1.30
32	3.2×2.5	2.10 to 2.50	1.10 to 1.30	1.90 to 2.30
42	4.5×2.0	2.50 to 3.20	1.80 to 2.30	1.50 to 1.80
43	4.5×3.2	2.50 to 3.20	1.80 to 2.30	2.60 to 3.00
52	5.7×2.0	4.20 to 4.70	2.00 to 2.50	1.50 to 1.80
55	5.7×5.0	4.20 to 4.70	2.00 to 2.50	4.20 to 4.70

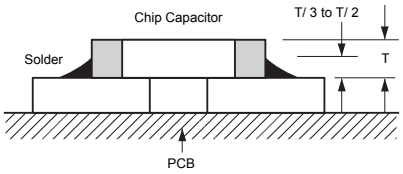
∗ CA series: Please refer applicable page.

Automotive Series

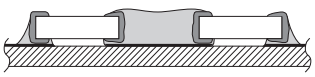
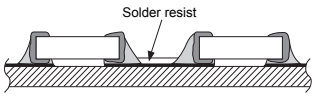
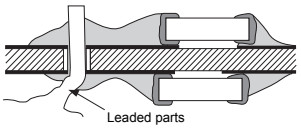
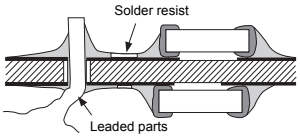
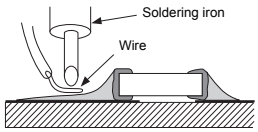
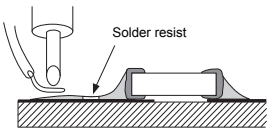
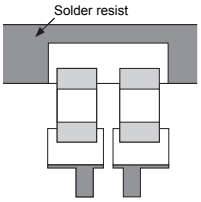
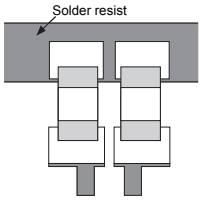
(Unit: mm)

Size	L×W	a	b	c
105	1.6×0.8	0.60 to 0.90	0.80 to 1.00	0.70 to 1.00
21	2.0×1.25	0.90 to 1.20	0.80 to 1.20	0.90 to 1.40
316	3.2×1.6	1.40 to 1.90	1.00 to 1.30	1.30 to 1.80

Ideal Solder Thickness



Typical mounting problems

Item	Not recommended example	Recommended example/ Separated by solder
Multiple parts mount		
Mount with leaded parts		
Wire soldering after mounting		
Overview		

Mounting Design

The chip could crack if the PCB warps during processing after the chip has been soldered.

Recommended chip position on PCB to minimize stress from PCB warpage

Actual Mounting

1) If the position of the vacuum nozzle is too low, a large force may be applied to the chip capacitor during mounting, resulting in cracking.
2) During mounting, set the nozzle pressure to a static load of 100 to 300 gf.
3) To minimize the shock of the vaccum nozzle, provide a support pin on the back of the PCB to minimize PCB flexture.

4) Bottom position of pick up nozzle should be adjusted to the top surface of a substrate which camber is corrected.
5) To reduce the possibility of chipping and cracks, minimize vibration to chips stored in a bulk case.
6) The discharge pressure must be adjusted to the part size. Verify the pressure during setup to avoid fracturing or cracking the chips capacitors.

Resin Mold

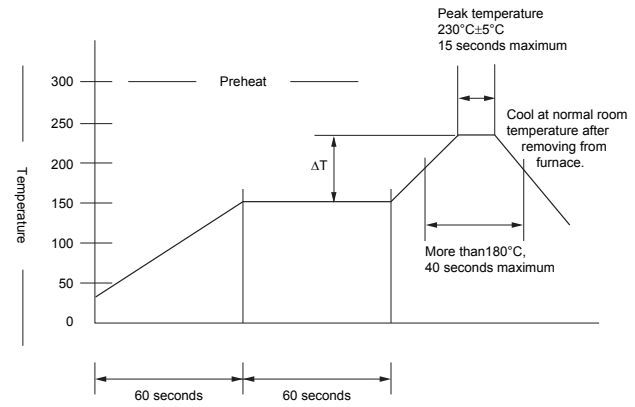
1) If a large amount of resin is used for molding the chip, cracks may occur due to contraction stress during curing. To avoid such cracks, use a low shrinkage resin.
2) The insulation resistance of the chip will degrade due to moisture absorption. Use a low moisture absorption resin.
3) Check carefully that the resin does not generate a decomposition gas or reaction gas during the curing process or during normal storage. Such gases may crack the chip capacitor or damage the device itself.

Soldering Method

1) Ceramic is easily damaged by rapid heating or cooling. If some heat shock is unavoidable, preheat enough to limit the temperature difference (Delta T) to within 130 degree Celsius.
2) The product size 1.0×0.5mm to 3.2×1.6mm can be used in reflow and wave soldering, and the product size of over 3.2×2.5mm, 0.6×0.3mm, and capacitor arrays can be used in reflow.
   Circuit shortage and smoking can be created by using capacitors which are used neglecting the above caution.
3) Please see our recommended soldering conditions.
4) In case of using Sn-Zn Solder, please contact us in advance.

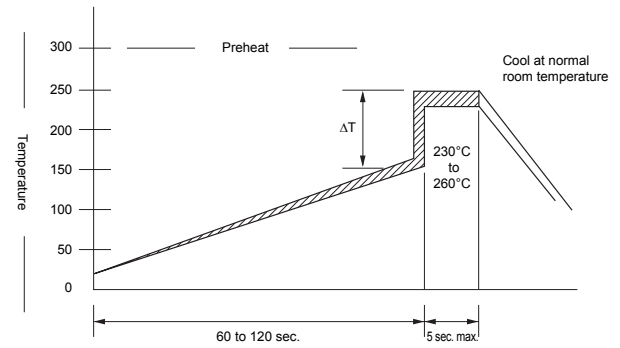
Recommended Temperature Profile (62Sn Solder)

Reflow



① Minimize soldering time.
② Ensure that allowable temperature difference does not exceed 150°C.
③ Ensure that allowable temperature difference does not exceed 130°C for 3.2×2.5mm size or larger.

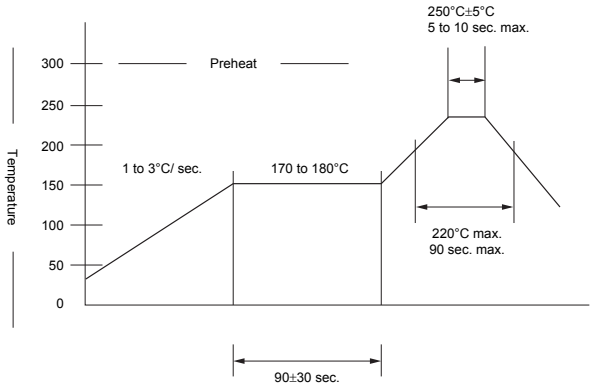
Wave



① Ensure that the chip capacitor is preheated adequately.
② Ensure that the temperature difference (ΔT) does not exceed 150°C.
③ Cool naturally after soldering.
④ Wave soldering is not applicable for chips with size of 3.2x2.5mm or larger.

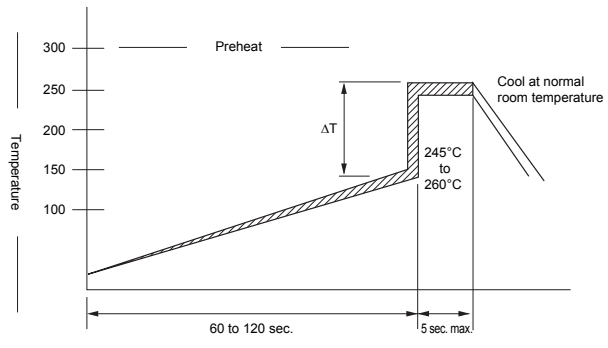
Recommended Temperature Profile (Sn–3Ag–0.5Cu)

Reflow



① Minimize soldering time.
② Ensure that allowable temperature difference does not exceed 150°C.
③ Ensure that allowable temperature difference does not exceed 130°C for 3.2×2.5mm size or larger.

Wave



① Ensure that the chip capacitor is preheated adequately.
② Ensure that the temperature difference (ΔT) does not exceed 150°C.
③ Cool naturally after soldering.
④ Wave soldering is not applicabel for chips with size of 3.2×2.5mm or larger.

Sodering iron

1) Temperature of iron chip	380°C max.
2) Wattage	80W max.
3) Tip shape of soldering iron	ϕ3.0mm max.
4) Soldering Time	3 sec. max.

5) Cautions
   a) Pre–heating is necessary Rapid heating must be avoided.
      Delta T≤150°C
   b) Avoid direct touching to capacitors.
   c) Avoid rapid cooling after soldering. Natural cooling is recommended.